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For Immediate Release

Paratek Introduces New RF Tunable Passive ICs

HIGHLY MINIATURIZED PARATUNE™ CIRCUITS BOOST PERFORMANCE OF WIRELESS DEVICES

Nashua, NH – March 7, 2007 – Paratek, a leading technology innovator of radio frequency (RF) components for mobile wireless applications, has introduced its ParaTune™ family of RF tunable passive ICs. The circuits have the ability to change capacitance at different voltages, making them ideally suited for RF wireless applications that demand frequency- or impedance-tuning. ParaTune passive ICs feature high linearity and high Q and are available in a wide range of capacitances and form factors to meet customer-specific needs.

The foundation for ParaTune passive ICs is ParaScan™, a BST-based proprietary material which provides high Q, low-loss electronic tuning. Voltage-tunable ParaScan outperforms other tunable technologies including pure BST, varactors, MEMS, and GaAs and will allow next-generation wireless products to operate more efficiently over a range of operating conditions and modes. Exceptionally fast switching speeds, high capacitance density, high Q, high linearity, and low harmonic emissions are just some of the advantages provided by Paratek's integrated capacitor circuits.

Jim DiLorenzo, President and CEO of Paratek, commented on how ParaTune passive ICs will help further the evolution of advanced wireless products. "Fixed or fixed-switched technologies are limiting and can force compromises in circuit design and performance. With ParaTune, we're harnessing the tremendous benefits of RF tuning to revolutionize the wireless industry. Our tunable passive ICs will pave the way for new multi-mode, multi-band wireless handsets that operate at an optimum level." DiLorenzo also noted

that ParaTune passive ICs will benefit the entire wireless community, including antenna designers, handset manufacturers, carriers, and the consumer.

ParaTune passive ICs work in conjunction with custom ASICs, which Paratek also produces. These ASICs produce the variable bias voltages that manage the tuning function of the passive ICs. ParaTune passive ICs also offer packaging flexibility and the advantages of high-volume production. Packaging options include bare die with gold-bond pads and fully-packaged versions using a land-grid-array (LGA) or ball-grid-array (BGA) flip chip format. Paratek will work collaboratively with customers to target custom capacitance values and packaging requirements.

Paratek will be demonstrating its advanced RF tuning technology at CTIA Wireless in Orlando, Florida. The conference, to be held March 27 through March 29 at the Orange County Convention Center, is the largest and most comprehensive trade show in the wireless industry. Paratek will be in meeting room **MR-127** for the duration of the show. To arrange a scheduled demonstration of the technology, please e-mail your request to ctia2007@paratek.com.

About Paratek

Paratek Microwave, Inc. designs and manufactures adaptive RF front-end component solutions for mobile wireless applications requiring multi-mode and multi-band operation. The Company is privately held and headquartered in Columbia, MD, with additional offices in Nashua, NH and Crystal Lake, IL. For more information about Paratek, visit the Company's website at www.paratek.com.

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